

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
Contact Info: [ti.com/support](https://ti.com/support)  
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
Created on: 06/12/2022

Details for "TPS75433QPWPR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS75433QPWPR	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	PWP   20	4.4x6.5x1.15	75.9

**\*Total Device Mass**  
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000283	3	0.000001	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000283	3	0.000001	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000566	6	0.000003	0
Precious Metals	Gold	7440-57-5	0.353175	99.997735	999977	0.46518	4652
Precious Metals	Silver	7440-22-4	0.000004	0.001133	11	0.000005	0
Sub-Total			0.353183	100	1000000	0.465191	4652
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.837865	85.000046	850000	1.103584	11036
Thermoplastics	Epoxy	85954-11-6	0.147858	14.999954	150000	0.194749	1947
Sub-Total			0.985723	100	1000000	1.298333	12983
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	27.85926	97.41	974100	36.694497	366945
Copper and Its Alloys	Iron	7439-89-6	0.6864	2.4	24000	0.904084	9041
Copper and Its Alloys	Phosphorus	7723-14-0	0.00858	0.03	300	0.011301	113
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00858	0.03	300	0.011301	113
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00858	0.03	300	0.011301	113
Zinc and Its Alloys	Zinc	7440-66-6	0.0286	0.1	1000	0.03767	377
Sub-Total			28.6	100	1000000	37.670154	376702
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.437552	95.12	951200	0.576316	5763
Precious Metals	Gold	7440-57-5	0.003588	0.78	7800	0.004726	47
Precious Metals	Palladium	7440-05-3	0.01886	4.1	41000	0.024841	248
Sub-Total			0.46	100	1000000	0.605884	6059
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	37.665795	88	880000	49.61106	496111
Other Plastics and Rubber	Carbon Black	1333-86-4	0.171208	0.4	4000	0.225505	2255
Thermoplastics	Epoxy	85954-11-6	4.965037	11.600001	116000	6.53964	65396
Sub-Total			42.80204	100	1000000	56.376204	563762
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.721228	100	1000000	3.584234	35842
Sub-Total			2.721228	100	1000000	3.584234	35842
Total			75.922174			100	1000000

**Important Note**  
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**  
TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.